

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20161115003 Datasheet for SN54HC541, SN74HC541 Information Only

Date: January 04, 2017

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE SN74HC541N SN74HC541NSR SN74HC541PWR **CUSTOMER PART NUMBER**

null null null

Technical details of this Product Change follow on the next page(s).

Title: Datasheet for SN54HC541, SN74HC541 Customer Contact: PCN Manager Dept: Quality Services Change Type: Assembly Site Design Wafer Bump Site Assembly Process Data Sheet Wafer Bump Material Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Fab Site Packing/Shipping/Labeling Test Process Wafer Fab Materials Description of Change: Texas Instruments Incorporated is announcing an information only notification etc. The product datasheet(s) is being updated as summarized below. The following change history provides further details. SN54HC541, SN74HC541 SCLS305D-JANUARY 1908-REVISED SEPTEMBER 2016		
Customer Contact: PCN Manager		
Change Type:		
Assembly Site Assembly Process Data Sheet Wafer Bump Material Assembly Materials Part number change Wafer Bump Process Wafer Fab Materials Wafer Fab Site Wafer Fab Materials Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification etc. The product datasheet(s) is being updated as summarized below. The following change history provides further details.		
Assembly Materials Mechanical Specification Test Site Packing/Shipping/Labeling Test Process Wafer Fab Site Wafer Fab Materials Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification etc. The product datasheet(s) is being updated as summarized below. The following change history provides further details. SN54HC541, SN74HC541		
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TEXAS SN54HC541, SN74HC541		
INSTRUMENTS SN54HC541		
INSTRUMENTS		
Changes from Revision C (August 2003) to Revision D		
Added Applications section, Thermal Information table, ESD Ratings table, Feature Description section, Device		
Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout		
section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section 1		
Deleted Ordering Information table, see Mechanical, Packaging, and Orderable Information at the end of the datasheet 1		
Changed R _{e,lA} for DB package from 70°C/W: to 90.2°C/W Changed R _{e,lA} for DB package from 50°C/W: to 90.2°C/W Changed R _{e,lA} for DB package from 50°C/W: to 90.2°C/W The second Research of the second researc		
Changed R _{BJA} for DW package from 58°C/W: to 77.5°C/W		
Changed R _{BJA} for NS package from 69°C/W: to 45.2°C/W Changed R _{BJA} for NS package from 60°C/W: to 72.8°C/W 5		
Changed R _{BJA} for PW package from 83°C/W: to 72.6 C/W Changed R _{BJA} for PW package from 83°C/W: to 98.3°C/W: 5		
Onlinged Naja for FW package from 65 G/W. to 50.5 G/W		
The datasheet number will be changing.		
Device Family Change From: Change To:		
SN54HC541, SN74HC541 SCLS305C SCLS305D		
These changes may be reviewed at the datasheet links provided.		
http://www.ti.com/product/SN54HC541		
Reason for Change:		
To more accurately reflect device characteristics.		
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):		
No anticipated impact. This is a specification change announcement only. There are no changes to		
the actual device.		
Changes to product identification resulting from this PCN:		
Changes to product identification resulting from this PCN: None.		
Changes to product identification resulting from this PCN: None. Product Affected:		
Changes to product identification resulting from this PCN: None. Product Affected: JM38510/65711BRA SN74HC541DWE4 SN74HC541N SN74HC541PWR		
Changes to product identification resulting from this PCN: None. Product Affected: JM38510/65711BRA SN74HC541DWE4 SN74HC541N SN74HC541PWR M38510/65711BRA SN74HC541DWG4 SN74HC541NE4 SN74HC541PWRG4		
Changes to product identification resulting from this PCN: None. Product Affected: JM38510/65711BRA SN74HC541DWE4 SN74HC541N SN74HC541PWR		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com